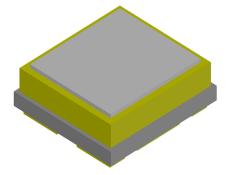
JSFON



# **OC-VC** series

## **Product Specification**

| Product     | 3532 VCSEL Emitter  |
|-------------|---------------------|
| Part Number | OCVC32-7258V9420-V0 |
| Issue Date  | 2019/10/14          |



#### Features

- Vertical Cavity Surface Emitting Laser technology
- Package size = 3.5mm x 3.2mm x 1.3mm
- Pulse Output power 2W emitter
- Peak wavelength  $\lambda_p$  =940nm
- Divergence angles= 72°x 58°
- Wavelength stabilized (0.07nm per °C)
- Narrow spectral width (<1nm)
- RoHS
- Photo Diode inside

## Applications

- 3D depth sensing
- Gesture sensing
- Flood illuminator



## **Product Nomenclature**

The product name is designated as below:

# VCAB – CDEFGHIJK

#### **Designation:**

#### Notes

| Designation  | n:                        |
|--|---------------------------|
| AB = Packag<br>CDEF = Dive<br>G = Internal (<br>HI = Waveler | ergence Angle (2)<br>Code |
| Notes  |                           |
| 1. Package   | e Size:                   |
| Symbol   | Description               |
| 32   | 3.5mm x 3.2mm             |
|  |                           |

#### 2. Divergence Angle:

| <b>U</b> | 5           |
|----------|-------------|
| Symbol   | Description |
| 5040     | 50° x 40°   |
| 6045     | 60° x 45°   |
| 7258     | 72° x 58°   |
| 9070     | 90° x 70°   |
| 1190     | 110° x 90°  |

#### 3. Wavelength:

| Symbol | Description |
|--------|-------------|
| 85     | 850nm       |
| 94     | 940nm       |

#### 4. Pulse mode Output Power:

| Symbol | Description |
|--------|-------------|
| 05     | 0.5W        |
| 10     | 1W          |
| 20     | 2W          |
| 30     | 3W          |
| 40     | 4W          |



## Maximum Ratings (Ta = 25 °C)

| Parameter  | Symbol           | Values             | Unit |
|--|------------------|--------------------|------|
| Operating temperature range                      | T <sub>op</sub>  | -20 ~ 85           | °C   |
| Storage temperature range                        | T <sub>stg</sub> | -40 ~ 85           | °C   |
| Maximum package SMT solder<br>Reflow temperature |                  | 260°C<br>10seconds | °C   |

## Characteristics(Ta = 25 °C)

| Parameter                      | Symbol          | Condition              | Min. | Тур. | Max. | Unit  |
|--------------------------------|-----------------|------------------------|------|------|------|-------|
| Pulse Output power             | Po              | I <sub>F</sub> = 3.0 A | 1700 | 2100 | -    | mW    |
| Wavelength                     | $\lambda_{p}$   | I <sub>F</sub> = 3.0 A | 930  | 940  | 950  | nm    |
| Forward Voltage                | Vf              | I <sub>F</sub> = 3.0 A | 1.7  | 2.0  | 2.3  | V     |
| Threshold current              | l <sub>th</sub> |                        | -    | 500  | -    | mA    |
| Power Conversion<br>Efficiency | PCE             | I <sub>F</sub> = 3.0 A | -    | 35   | -    | %     |
| Wave Shift                     | ∆λ/∆Τ           | I <sub>F</sub> = 3.0 A | -    | 0.07 | -    | nm/°C |
| Slope Efficiency               |                 |                        | -    | 0.84 | -    | W/A   |

Note:

- Forward Voltage tolerance is ±0.1 V, Radiant Intensity tolerance is ±10% Others measurement allowance is ±10%.
- 2. VCSEL is mounted on PCB and measured with operating bias current @ 3A,10ms
- 3. Due to the special conditions of the manufacturing processes of VCSEL, the typical data of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.

## Photodiode Electrical / Optical Characteristics(Ta = 25 °C)

| Parameter                 | Symbol         | Condition               | Min. | Тур. | Max. | Unit |
|---------------------------|----------------|-------------------------|------|------|------|------|
| Forward Voltage           | Vf             | I <sub>F</sub> = 10 mA  | 0.5  |      | 1.3  | V    |
| Reverse Breakdown Voltage | $V_{BR}$       | I <sub>R</sub> = 100 uA | 35   |      |      | V    |
| Reverse Dark Current      | I <sub>D</sub> | V <sub>R</sub> = 10 V   |      | 2    | 10   | nA   |
| Light Current             | ΙL             | $V_R = 5 V$             |      | 0.5  |      | uA   |
| Peak Sensing Wavelength   | $\lambda_{p}$  |                         |      | 940  |      | nm   |



## Radiometric Power Bin Structure at 3000mA

| or       | Bin Code           | Minimum<br>Radiometric Power (mW)  | Typical<br>Radiometric Power (mW) |
|----------|--------------------|--|-----------------------------------|
| red 940  | B2                 | 1700   | 2100                              |
| The flux | bin of the product | e of ±10% on flux and power measure<br>may be modified for improvement with<br><b>gth Bin Structure at</b> | nout notice.                      |
|          |                    |  |                                   |
| Color    | Bin Code           | Centroid Wavelength  |                                   |
| Color    |                    | -  |                                   |

## Forward Voltage Bin Structure at 3000mA

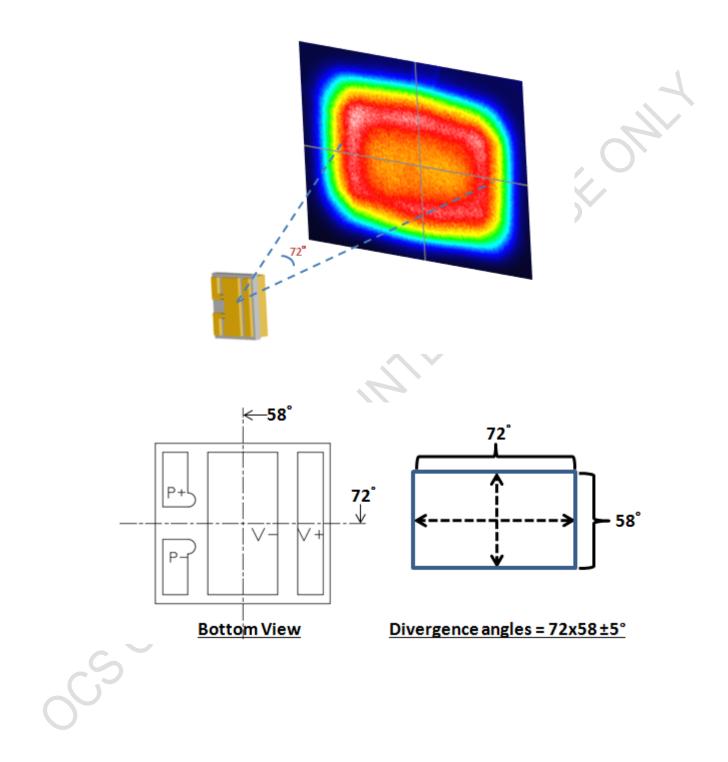
| Color        | Bin Code | Typical Voltage (V) | Maximum Voltage (V) |
|--------------|----------|---------------------|---------------------|
| Infrared 940 | A1       | 2.0                 | 2.3                 |

• OCS maintain a tolerance of ±0.1V for Voltage measurements.

acs contrib.



Divergence angles corresponds to the direction

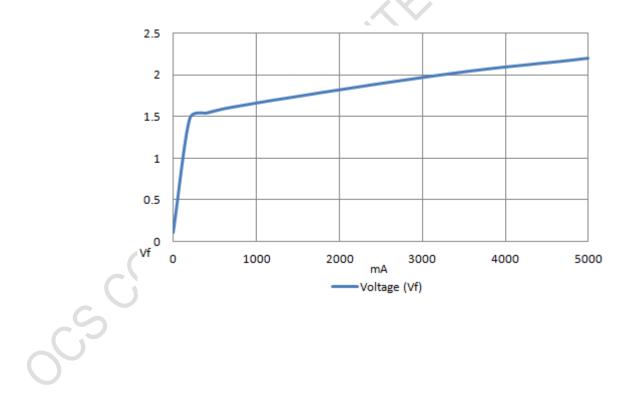


## Pulse Output Power vs. Forward Current

**DRIENT-CHIP** 

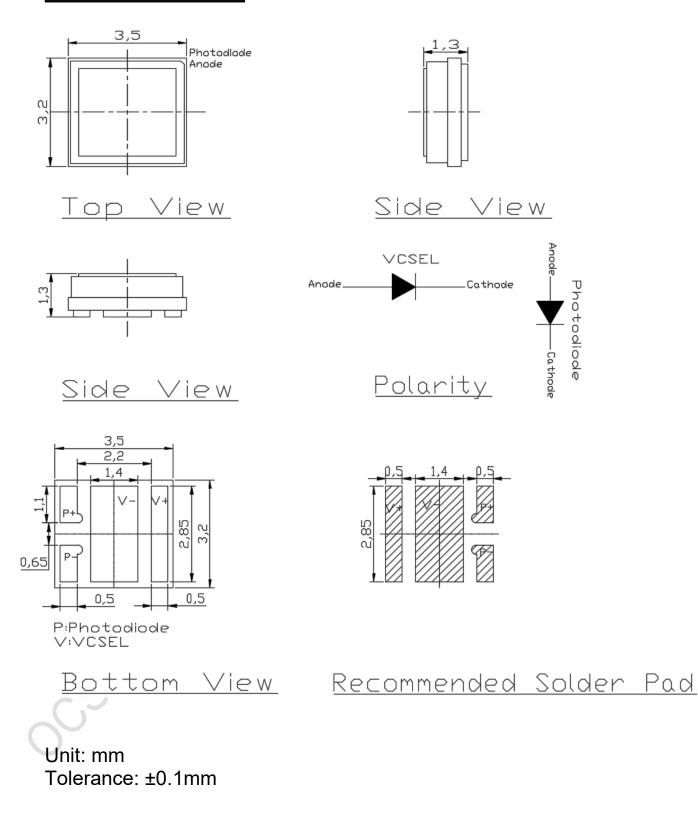
5000 45.0% 4500 40.0% 4000 35.0% 3500 30.0% 3000 25.0% 2500 20.0% 2000 15.0% 1500 10.0% 1000 5.0% 500 mW<sup>0</sup> 0.0% PCE 0 1000 1500 2000 2500 3000 3500 4000 4500 5000 500 mA Power (mW) PCE (%)

## ■ Forward Voltage vs. Forward Current





■ <u>Outline Dimension</u>





- Cleaning
- 1. If washing is required, recommend to use alcohol as a solvent.
- 2. Recommend to avoid cleaning the VCSEL by ultrasonic. If necessary, pre-test the VCSEL is necessary to confirm whether any damage occur after the process.

## Precautions for use

#### 1. Over-current-proof

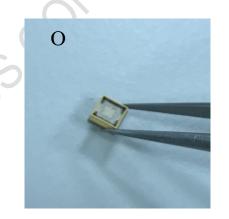
1.1 Customer must apply resistors for protection; otherwise slight voltage shift will cause big current change (Burn out will happen).

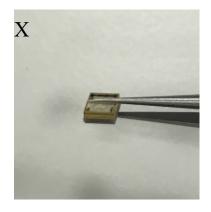
#### 2. Storage

- 2.1 Do not open moisture proof bag before the products are ready to use.
- 2.2 Before opening the package: The VCSEL should be kept at 30°C or less and 90%RH or less.
- 2.3 After opening the package: The VCSEL floor life is 1 year under 30°C or less and 60% RH or less. If unused VCSEL remain, it should be stored in moisture proof packages.
- 2.4 If the moisture absorbent material (silica gel) has faded away or the VCSEL have exceeded the storage time, baking treatment should be performed using the following conditions. Baking treatment: 60±5°C for 24 hours.

#### 3. Handling indications

3.1 During processing, mechanical stress on the surface should be minimized as much as possible. Sharp objects of all types should not be used to pierce the sealing compound. In general, VCSEL should only be handled at the housing. This also applies to VCSEL without a diffuser, since the surface can also become scratched.

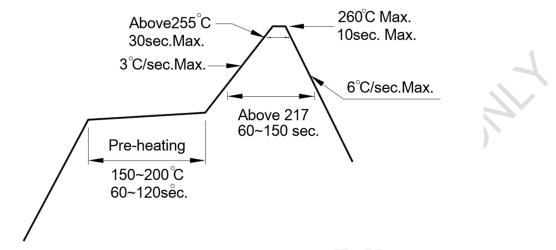






#### 4. Soldering Condition

4.1 Pb-free solder temperature profile (JEDEC-STD-020 latest version compliant)



- 4.2 Reflow soldering should not be done more than two times.
- 4.3 When soldering, do not put stress on the VCSEL during heating.
- 4.4 After soldering, do not warp the circuit board.

#### 5. Soldering Iron

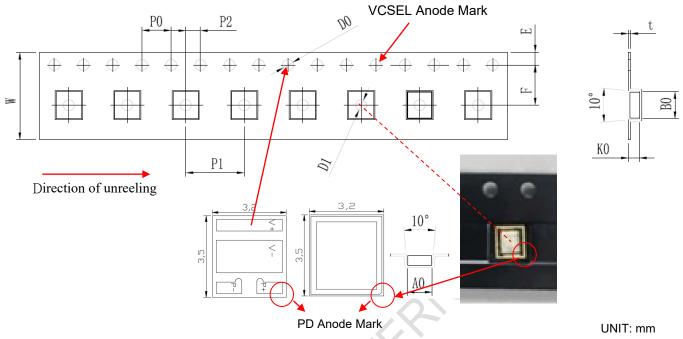
5.1 Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

#### 6. Repairing

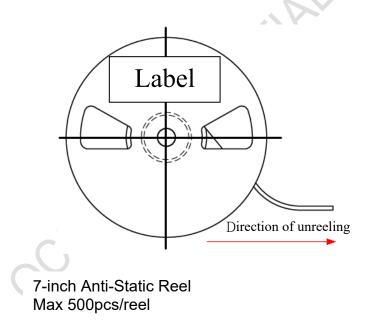
6.1 Repair should not be done after the VCSEL have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the VCSEL will or will not be damaged by repairing.



Carrier Taping



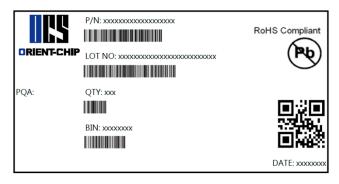
| symbol | Ao        | Во        | Ko            | Po            | P1         | P2        | Т         |
|--------|-----------|-----------|---------------|---------------|------------|-----------|-----------|
| spec   | 3.45±0.10 | 3.75±0.10 | 1.50±0.10     | 4.00±0.10     | 8.00±0.10  | 2.00±0.10 | 0.30±0.05 |
| symbol | E         | F         | Do            | D1            | W          | 10Po      |           |
| spec   | 1.75±0.10 | 5.50±0.10 | 1.50+0.10-0.0 | 1.50±0.10-0.0 | 12.00±0.30 | 40.0±0.10 |           |



IS

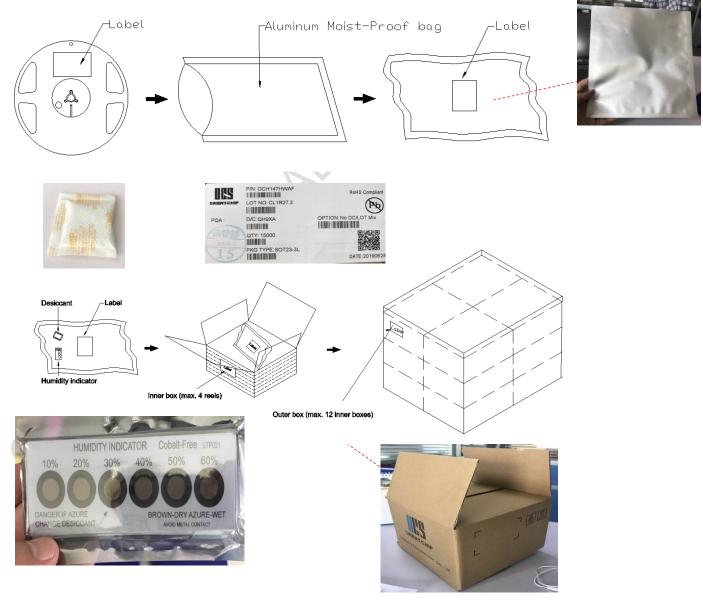


## Product Labeling



- P/N: OCS Product Model Name
- LOT: Lot Number
- QTY: Q'ty
- BIN: mW/nm/Vf ( ex.[A1/94/V1] )
- DATE: Enter the warehouse

## Moisture Resistant Packing





#### Modified records

| ■ <u>Mo</u> | odified rec | <u>ords</u>    |            |
|-------------|-------------|----------------|------------|
|             |             |                |            |
|             | Version     | Description    | Issue Date |
|             | V0          | New spec       | 2019/03/20 |
|             | V1          | Add Ith, Slope | 2019/10/05 |
|             | V2          | Update spec    | 2019/10/14 |
|             | S           |                |            |